CLAIMS:

1. A wafer bonding method comprising:

applying a bonding composition to either a first substrate or a second substrate by spin-coating, said layer being a uniform material across the thickness formed of the same composition; and

bonding the first and second substrates together via the bonding layer, wherein the composition comprises a cycloolefin copolymer.

2. The method of claim 1, wherein the first substrate is an active wafer with an active surface comprising topographical features, on which the layer is applied.

3. The method of claim 2, wherein the bonding composition flows into and over the topographical features.

4. The method of claim 2, wherein the bonding layer forms a uniform layer over the topography of the active surface.

5. The method of claim 1, wherein the bonding layer is applied in that the thickness T of the bonding layer varies by less than about 20%, preferably less than about 10%, more preferably by less than about 5%, even more preferably by less than about 2%, and most preferably less than about 1% across the length of the second substrate.

6. The method of claim 1, wherein the bonding layer is applied by spray-coating.